

# Protection Against Electrostatic Discharges (ESD)

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Agenda

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- Electrostatic discharge ESD Introduction
- ESD Models
- Protection Structures
- Practical Examples Measurement, Simulation





### Introduction to ESD

#### ESD at the gas station



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#### LLEE Elektrostatic Discharge (ESD)







### **Electrostatic Discharge - Introduction**

Among all transient disturbances ESD is still one of the most important reliability problems in the semiconductor industry and one should never overlook the damage that has been caused by this re-balancing of charge between objects brought into close contact.



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### **Electrostatic Discharge - Introduction**

Where does electrostatic charge come from?

### Triboelectric charging

Mechanical contact and separation (e.g. walking on a carpet)

### Ionic charging

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Not properly balanced Air Ionizer

#### Direct charging

Mobile charge transfer Plug a cable to an IC (e.g. USB to PC)

### Field induced charging

IC brought into an electric field





### ESD Test Models - History

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- Back in the 1960's, the first ESD model, which was used to stress IC's was the HBM (Human Body Model).
- But soon it has been noticed that the HBM could not explain all ESD failures and with the increasing use of automated handling machines the *MM* (*Machine Model*) has been introduced.
- Still other types of ESD damage exist, which can not be covered by these two test models. For example when an IC slides down a shipping tube it becomes charged and it will be discharged when it hits a grounded steel table.

Therefore the **CDM (Charged Device Model)** was developed in the early eighties to explain this type of damage.





### IC Level ESD Test Models (1)

Human Body Model (HBM):

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**Test levels:** 250V – 8kV (2kV)







### IC Level ESD Test Models (2)

Machine Model (MM):

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It describes an ESD stress, which is caused by a machine during the handling of an IC (i.e. metallic machinery in an IC manufacturing or testing process).

Test levels: 100V - 800V (200V)





Discharge current waveform into a short wire (200V ESD)





### IC Level ESD Test Models (3)

Charged Device Model (CDM):

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It describes an ESD stress, that occurs during the manufacturing and assembly processes, where the IC charges when it slides down a feeder in a tester or a shipping tube.

**Test levels:** 125V – 2kV (500V)



Discharge current waveform into a short wire (500V ESD)





### System Level ESD Test Models (1)

Gun Model (HBM) for Automotive according to ISO10606:



It describes the discharge procedure of a human person either directly or through a metallic part (e.g. tool, key, stick,...).

#### **Test levels:**

IIFE

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Contact discharge: 3kV – 20kV Air discharge: 4kV – 25kV

- 330pF: Applications accessed only from the inside of the vehicle
- 150pF: Applications accessed only from the outside of the vehicle
- 2000 $\Omega$ : Discharge of a human body directly through the skin

330 $\Omega$ : Discharge of a human body through a metallic part (e.g. tool, key, stick,...)



Discharge current waveform into a  $2\Omega$  current target of the GUN  $330pF/2000\Omega$ , GUN  $330pF/330\Omega$ , GUN  $150pF/2000\Omega$ , and GUN  $150pF/330\Omega$  model for a (2kV ESD)





#### IFE IC Level vs. System Level ESD Discharge current waveform of a 2kV ESD $HBM \neq HBM$ 8.0 System-level 7.0 (IEC61000-4-2: 3300hm, 150pF) 6.0 5.0 **IC-level** (¥ 4.0 (JESD22-A11E: 15000hm, 100pF) 3.0 2.0 1.0 0.00 0.00 40n 80n 120n 160n 200n

Discharge current waveform of a 2kV system-level (EN 61000-4-2) and IC-level (JESD22-A114E) HBM ESD pulse

time (s)





## ESD Pulse Simulation (1)

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Simulation model according to IEC 61000-4-2 - ESD (electrostatic discharge)



	Compo nent	Value	Function	Modeling method
Group 1	C3	20 pF, PCB board	Pulse forming R-C-R filter, L3 is	C: Two metal layers with dielectric material in between
	R3	36 $\Omega$ , lumped	its loop inductance	R: Single cell, $\sigma = 13.9$ S/m.
Rise- time	L3	About 6 nH, distributed	Loop inductance	The loop's geometry is part of the ESD generator geometry model.
	C4	In the SPICE model 15 pF, distributed	Capacitance between discharge tip and ground plane.	The geometry model includes the structural elements.
	C5	In the SPICE model 20 pF, distributed	Capacitance between the simulator body and the ground plane.	The geometry model includes the structural elements.
Group 2 Pulse width and height	C2	In the SPICE model 5 pF, distributed	Influences the width of the initial pulse	This capacitance is simulated by the structure itself.
	R2	120 $\Omega$ , lumped		Single cell, $\sigma = 0.9$ [S/m].
Group 3 Falling edge	C1	110 pF, lumped	Determines the tail of the waveform. L1,	C: Two metal layers with dielectric material in between
	R1	330 $\Omega$ , lumped	the ground strap loop inductance, is estimated to be 3500 nH (rectangular loop	Single cell $\sigma = 0.756$ S/m
	L1	3500 nH, distributed		The ground strap is included in the numerical model geometry.
			assumption).	

 K. Wang, D. Pommerenke, R. Chundru, T. Doren, J. Drewniak, A. Shashindranath: Numerical Modeling of Electrostatic Discharge Generators, IEEE Transactions on Electromagnetic Compatibility, Vol. 45, No. 2, May 2003, pp 258-271





#### IIFE ESD Pulse Simulation (2)

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### Simulation in LTSPICE: Discharge waveform into a 2 Ohm resistor



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Over current protection

**Thermistor (PTC)** 







Transient Voltage Suppressor (TVS)



TVS diodes are specially designed for a controlled breakdown that allows the current to keep the voltage across the diode.

Typical V/I characteristic (uni-directional)



uni-directional bi-directional

- + very fast response times (sub ns)
- + do not wear out
- low surge capability
- leakage current





# Protection Elements (3)

#### Gas Discharge Tube (GDT)







### Protection Elements (4)

#### Voltage Dependent Resistor (VDR) - Varistor



Zinc oxide grains

Microvaristor (breakdown voltage 2-5V)

Intergranular boundary

The electrical behavior of the MOV results from the number of microvaristors connected in series or in parallel.

#### Typical V/I characteristic

- + fast response times (ns)
- + low standby power
- + capacitance
- low surge capability
- leakage current
- capacitance

$$I = K \cdot V^{\alpha}$$

K geometry factor  $\alpha$  nonlinearity exponent depending on the material







## Quiz (1)

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#### Which ESD protection element is the best?

## 1.) 2.) 3.) 4.) 5.)







Quiz (2)

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#### Participate to this quiz with the following link:

# www.fbr.io/esd





### Appendix – ESD Standards

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- IEC 61000-4-2 ED2.0: Electromagnetic compatibility (EMC) Part 4-2: Testing and measurement techniques - Electrostatic discharge immunity test, 2008-12-09
- MIL-STD-883D Method 3015.7: Electrostatic Discharge Sensitivity Classification, Microelectronic Test Method Standard, Defense Supply Center Columbus (DSCC), US Department of Defense 1991
- JEDEC JESD22-A114-B: Electrostatic Discharge Sensitivity Testing Human Body Model, Electronics Industries Alliance, JEDEC 2000
- ANSI/ESD STM5.1-2001: Electrostatic Discharge Sensitivity Testing -Human Body Model (HBM) Component Level, ESD Association, 1998
- AEC-Q100-002-Rev C: Human Body Model Electrostatic Discharge Test, Automotive Electronics Council, AEC, 1998
- ISO 10605:2007(E): Road vehicles Test methods for electrical disturbances from electrostatic discharge, ISO, 2007

